

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 to 10 (cancelled).

Claim 11 (currently amended): A method for processing one or more components of gas turbines ~~prior to and/or during further processing of same~~, comprising:

heating a component of a gas turbine with at least one laser device; and
laser hardfacing the component with a separate laser device, the heating occurring prior to and/or during the laser hardfacing.

Claim 12 (previously presented): The method as recited in Claim 11, wherein the component is irradiated at least on one side by the at least one laser device.

Claim 13 (previously presented): The method as recited in Claim 11, wherein the at least one laser device includes a first laser device and a second laser device, and wherein the step of heating comprises irradiating the component on two sides from two irradiation directions using laser radiation, the first laser device being used for one irradiation direction and the second laser device being used for the other irradiation direction.

Claim 14 (previously presented): The method as recited in Claim 11, wherein the at least one laser device includes a plurality of laser devices, and wherein the step of heating comprises irradiating the components on all sides from multiple irradiation directions using laser radiation, one laser device being used for each irradiation direction.

Claim 15 (previously presented): The method as recited in Claim 11, further comprising adjusting angles of incidence at which laser radiation hit a surface of the component to the contour of said surface.

Claim 16 (previously presented): The method as recited in Claim 14, further comprising adjusting angles of incidence at which laser radiation from the plurality of laser devices hit a plurality of surfaces of the component to the contour of each surface.

Claim 17 (previously presented): The method as recited in Claim 11, further comprising measuring a temperature of the component, and, as a function thereof, adjusting such the power of the laser device to achieve an intended temperature setpoint value.

Claim 18 (previously presented): The method as recited in Claim 14, further comprising measuring a temperature of the component, and, as a function thereof, adjusting such the power of each laser device to achieve an intended temperature setpoint value.

Claim 19 (previously presented): The method as recited in Claim 17, wherein the heating and measuring steps are performed without contacting the component.

Claim 20 (previously presented): The method as recited in Claim 11, wherein one or multiple diode laser(s) are used as the at least one laser device.

Claim 21 (previously presented): The method as recited in Claim 11, further comprising subjecting the component to further processing after or during heating.

Claim 22 (canceled).